The most versatile product in our ThinkEdge portfolio.

SE10 Series

Lenovo

ThinkEdge

These compact yet powerful devices balance environmental requirements with reliable performance and effortless deployment and maintenance. This technology was created to solve some of the toughest challenges you face when it comes to capturing data at the outermost edge for your business. From extreme temperatures to the most constrained spaces, SE10 users can now scale the spectrums of ruggedness and flexibility thanks to the ground up modular design.



Unconstrained Entry Performance

Intel ATOM dual and quad core processors allow these compact, yet powerful edge clients to perform unconstrained.



Modular Design

The SE10 addresses variations with a ground up modular design, allowing users to scale up and down the spectrums of ruggedness and flexibility.



Easy Deployment and Maintenance

Compatible design to meet VESA, DIN, ThinkCentre Tiny mounting and 3 years life cycle.



Environmental Adaptability

Purposefully designed & Mil-STD compliant to be configured to adapt to a broad range of Edge vertical applications.

Popular Use Cases:









SE10

Series Packs A Punch

No edge environment is created exactly the same, and the features and functionalities you need from your edge devices often vary. This is why we're changing the game in versatility within our ThinkEdge portfolio.





Compact



Powerful





Adaptable

ThinkEdge SE10

Computing Versatility



OS Win10 IoT LTSC Ubuntu Server, Ubuntu Core
CPU Intel ATOM Elkhart 6/12W (up to 4 Cores)
RAM 2x So-DIMM up to 32GB DDR4 Memory

Storage 1x M.2 SSD up to 1T, 1x SD

Form Factor 0.8L Fanless, Ruggedized, Option IP50 kits

Connectivity USB, Serial, HDMI, DP, GbE, Wi-Fi, 4G

Power 110/220 AC adapter

Temp range 0~50C

Use Cases:

Retail, Hospitality, QSR Smart Spaces, Building Automation

ThinkEdge SE10-I

Computing Reliability



OS Win10 IoT LTSC Ubuntu Server, Ubuntu Core

CPU Intel ATOM Elkhart 6W (2 Cores)

RAM 2x So-DIMM up to 32GB DDR4 Memory

Storage 64GB eMMC, 1x M.2 SSD up to 1T, 1x SD

Form Factor 1.4L Fanless, Ruggedized, Option IP50 kits

I/O: 4xUSB, 2xSerial, HDMI, DP, 2xGbE, MIC-in, Line-out

I/O option: DIO, CAN or Serial or PoE

Wireless: Wi-Fi/BT, 4G
Power: 9~36V DC input

Temp range: -20°-60°C

Use Cases:

Manufacturing, Logistics, Smart Spaces, Building Automation

